



Form Type	Distribute	Version	2.0	Ref	IPC 1752A	Sectionals	Material Info	Subsectionals	D, A
Supplier Information									
Company Name	TE Connectivity	Request Document ID		Contact Name	Benfer, David W	Contact Title	Prod Compliance Engineer		
Company Unique ID	TE Connectivity	Response Date	2016-05-10	Contact Email	dave.benfer@te.com				
Contact Phone Number	717-986-3725								
Legal Statement									
Supplier Acceptance	true								
Legal Statement									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
Product									
Manufacturer Item number	2286237-1	Amount	48.0678	Version	-	Identity			
Manufacturer Item Name	BLOCK SIM CARD CONNECTOR	Weight Uom	mg	Mfr Site		Authority			
Date		UOM	Each						
EUroHS-0508	Product(s) meets EU RoHS requirement without any exemptions								
ChinaRoHS-0508	Product(s) is eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products								
EUREACH-0615	REACH Candidate Substances of Very High Concern ARE NOT Contained in the Product Above the Limits per the Definition within REACH								
Product Disclosure									
Sub-Item/Material/Substance	Level	Name	Substance Category	Substance CAS	Substance Concentration	Quantity	Mass per Unit	UOM	Exemption
Sub-Item	1	INSERT-MOLD HOUSING FOR BLOCK SIM CONN				1.0	48.0678	mg	
Material	2	Nickel Plate				1.0	2.1	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.0021	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.2	1.0	0.0042	mg	
Substance	3	Nickel	Nickel	7440-02-0	99.7	1.0	2.0937	mg	
Material	2	Gold Plate				1.0	0.0378	mg	
Substance	3	Gold	Supplier	7440-57-5	99.0	1.0	0.037422	mg	
Substance	3	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-0909	1.0	1.0	3.78E-4	mg	
Material	2	Palladium-Nickel Plate				1.0	0.13	mg	
Substance	3	Palladium	Supplier	7440-05-3	80.0	1.0	0.104	mg	
Substance	3	Nickel	Nickel	7440-02-0	20.0	1.0	0.026	mg	
Material	2	LCP-(MD+GF)30				1.0	18.6	mg	
Substance	3	Carbon black	Supplier	1333-86-4	1.0	1.0	0.186	mg	
Substance	3	Phenol	Supplier	108-95-2	0.0040	1.0	7.44E-4	mg	
Substance	3	Glass, oxide, chemicals	Supplier	65997-17-3	10.0	1.0	1.86	mg	
Substance	3	1,4-Benzenedicarboxylic acid, polymer with [1,1-biphenyl]-4,4-diol, 4-hydroxybenzoic acid and 6-hydroxy-2-naphthalenecarboxylic acid, acetate, potassium salt	Supplier	132699-78-6	66.996	1.0	12.46126	mg	
Substance	3	Mica-group minerals	Supplier	12001-26-2	22.0	1.0	4.092	mg	
Material	2	Copper				1.0	27.2	mg	
Substance	3	Lead	Lead/Lead Compounds	7439-92-1	0.1	1.0	0.0272	mg	
Substance	3	Beryllium	Supplier	7440-41-7	0.0010	1.0	2.72E-4	mg	
Substance	3	Silicon	Supplier	7440-21-3	1.0	1.0	0.272	mg	

Substance	3	Copper	Supplier	7440-50-8	94.7985	1.0	25.78519	mg	
Substance	3	Antimony	Supplier	7440-36-0	0.01	1.0	0.00272	mg	
Substance	3	Chromium	Supplier	7440-47-3	0.015	1.0	0.00408	mg	
Substance	3	Arsenic	Supplier	7440-38-2	0.015	1.0	0.00408	mg	
Substance	3	Manganese	Supplier	7439-96-5	0.05	1.0	0.0136	mg	
Substance	3	Cobalt	Supplier	7440-48-4	2.0	1.0	0.544	mg	
Substance	3	Mercury	Mercury/Mercury Compounds	7439-97-6	5.0E-4	1.0	1.36E-4	mg	
Substance	3	Cadmium	Cadmium/Cadmium Compounds	7440-43-9	0.01	1.0	0.00272	mg	
Substance	3	Nickel	Nickel	7440-02-0	2.0	1.0	0.544	mg	